

MSKSEMI

SEMICONDUCTOR



ESD



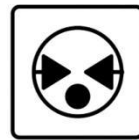
TVS



TSS



MOV



GDT



PLED

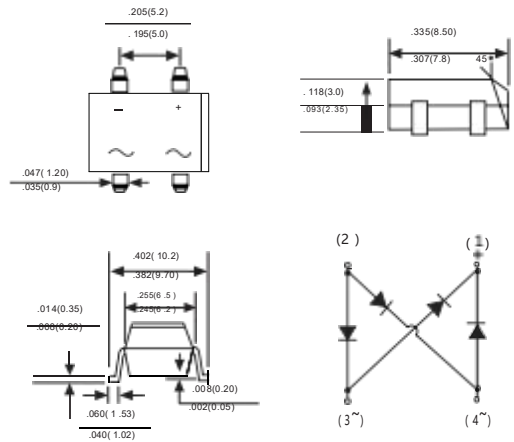
Product data sheet
Product data sheet

Features

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°/ 10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability

Mechanical Data

- Case :** JEDEC DBS Molded plastic body
- Terminals :** Solder plated, solderable per MIL- STD- 750 , Method 2026
- Polarity :** Polarity symbol marking on case
- Mounting Position :** Any
- Weight :** 0 .02 ounce, 0 .4 grams



Dimensions in inches and (millimeters)

REEL SPECIFICATION

P/N	PKG	QTY
DF005S-DF10S	DBS	1500

Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20% .

Parameter	SYMBOL	DF005S	DF01S	DF02S	DF04S	DF06S	DF08S	DF10S	UNITS
		S							
Marking Code									
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_c=40^{\circ}C$	$I_{F(AV)}$	1.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50							A
Maximum instantaneous forward voltage drop per leg at 1A	V_F	1.1							V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^{\circ}C$ $T_A=100^{\circ}C$	I_R	10 500							μA μA
Operating temperature range	T_J	-55 to + 150							$^{\circ}C$
storage temperature range	T_{STG}	-55 to + 150							$^{\circ}C$

NOTES:DBS for surface mount package.

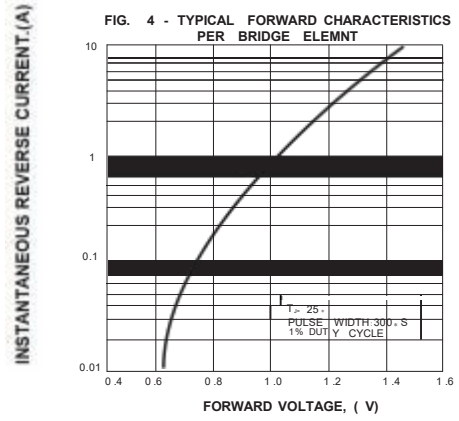
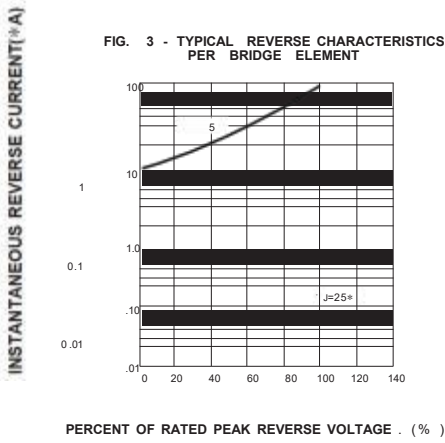
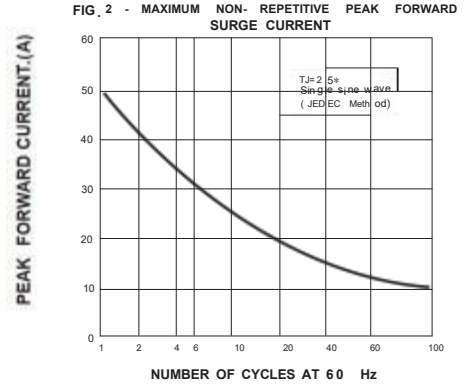
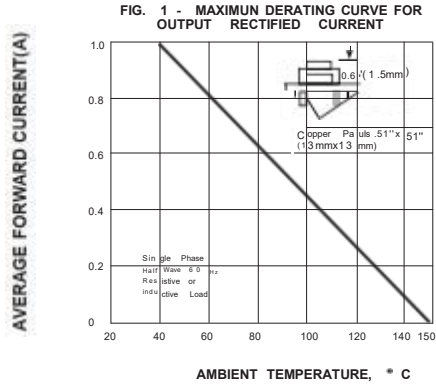
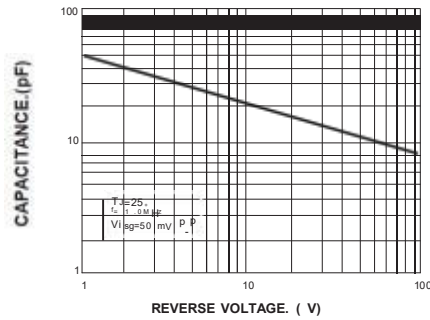


FIG. 3 - TYPICAL JUNCTION CAPACITANCE PER BRIDGE ELEMENT



The curve above is for reference only.

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